

- **★** Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent Cdv/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary



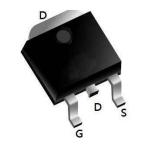
BVDSS	RDSON	ID
100V	85 mΩ	15A

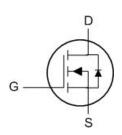
Description

The XR15N10 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The XR15N10 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

TO252-3L Pin Configuration





Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	100	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	15	А
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	8	А
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	3	А
ID@TA=70°C	Continuous Drain Current, V _{GS} @ 10V ¹	2.4	А
I _{DM}	Pulsed Drain Current ²	20	А
EAS	Single Pulse Avalanche Energy ³	6.1	mJ
las	Avalanche Current	10	А
P _D @T _C =25°C	Total Power Dissipation ³	30	W
P _D @T _A =25°C	Total Power Dissipation ³	2	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹		62	°C/W
Rejc	Thermal Resistance Junction-Case ¹		6.6	°C/W



Electrical Characteristics (TJ=25°C unless otherwise specified)

Symbol	Parameter Test Condition		Min.	Тур.	Max.	Units			
Off Characteristic									
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	100	-	-	V			
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =100V, V _{GS} =0V,	-	-	1.0	μA			
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA			
On Charac	On Characteristics								
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.5	2.5	V			
В	Static Drain-Source on-Resistance	V _{GS} =10V, I _D =5A	-	85	110	mΩ			
$R_{DS(on)}$	note3	V _{GS} =4.5V, I _D =3A	-	96	140	mΩ			
Dynamic C	Characteristics								
C _{iss}	Input Capacitance	\\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	-	765	-	pF			
Coss	Output Capacitance	V _{DS} =25V, V _{GS} =0V, f=1.0MHz	-	38	-	pF			
C _{rss}	Reverse Transfer Capacitance	1-1.0IVINZ	-	33	-	pF			
Qg	Total Gate Charge	\/ =E0\/ =2A	-	18	-	nC			
Q _{gs}	Gate-Source Charge	V_{DS} =50V, I_{D} =2A, V_{GS} =10V	-	2.5	-	nC			
Q_{gd}	Gate-Drain("Miller") Charge	VGS-10V	-	4	-	nC			
Switching	Characteristics								
t _{d(on)}	Turn-on Delay Time		-	7.5	-	ns			
t _r	Turn-on Rise Time	V _{DS} =50V, I _D =3A,	-	6	-	ns			
t _{d(off)}	Turn-off Delay Time	R _G =1.8Ω, V _{GS} =10V	-	21	-	ns			
t _f	Turn-off Fall Time		-	9	-	ns			
Drain-Sou	rce Diode Characteristics and Maxim	um Ratings							
	Maximum Continuous Drain to Source	Diode Forward			40				
Is	Current			-	10	Α			
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			_	40	Α			
V _{SD}	Drain to Source Diode Forward Voltage V _{GS} =0V, I _S =10A		-	-	1.2	V			
trr	Body Diode Reverse Recovery Time		-	21	-	ns			
Qrr	Body Diode Reverse Recovery Charge	I _F =3A, dl/dt=100A/µs	-	22	-	nC			

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : T_J=25 $^{\circ}\!\!\mathrm{C}$,V_DD=30V,V_G=10V,L=0.5mH,Rg=25 $\!\Omega$,I_As=4A

3. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%



Typical Performance Characteristics

Figure1: Output Characteristics

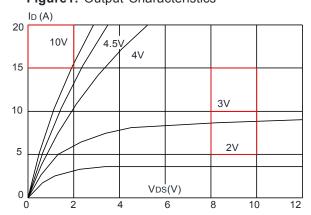


Figure 3:On-resistance vs. Drain Current

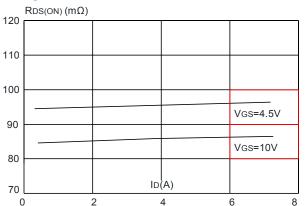


Figure 5: Gate Charge Characteristics

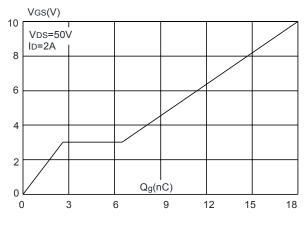


Figure 2: Typical Transfer Characteristics

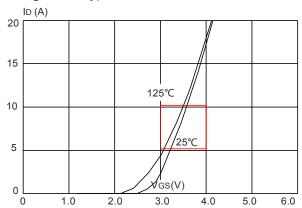


Figure 4: Body Diode Characteristics

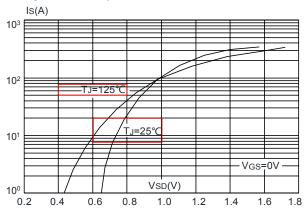


Figure 6: Capacitance Characteristics 10⁴ C(pF)

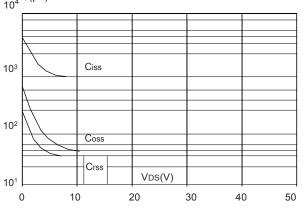




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

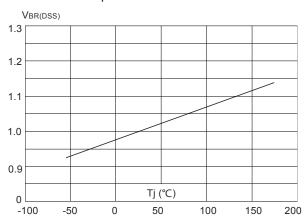


Figure 9: Maximum Safe Operating Area

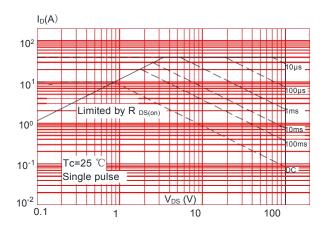
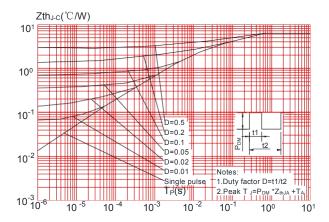


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



N-Ch 100V Fast Switching MOSFETs

Figure 8: Normalized on Resistance vs. Junction Temperature

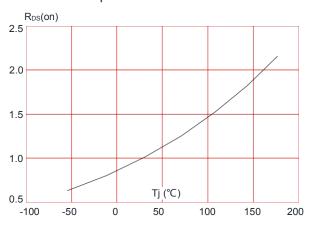
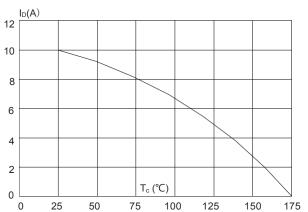
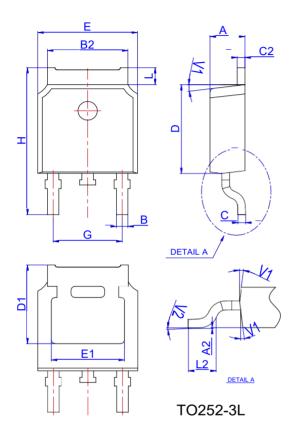


Figure 10: Maximum Continuous Drain Current vs. Case Temperature



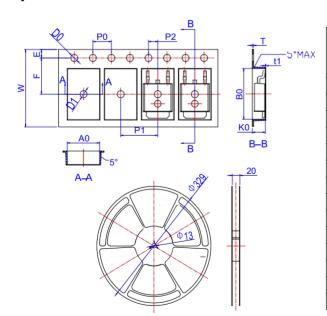


Package Mechanical Data TO252-3L



	Dimensions					
	Dimensions					
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
В	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
С	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
Н	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Reel Spectification-TO252-3L



	Dimensions						
D-f							
Ref.	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
W	15.90	16.00	16.10	0.626	0.630	0.634	
Е	1.65	1.75	1.85	0.065	0.069	0.073	
F	7.40	7.50	7.60	0.291	0.295	0.299	
D0	1.40	1.50	1.60	0.055	0.059	0.063	
D1	1.40	1.50	1.60	0.055	0.059	0.063	
P0	3.90	4.00	4.10	0.154	0.157	0.161	
P1	7.90	8.00	8.10	0.311	0.315	0.319	
P2	1.90	2.00	2.10	0.075	0.079	0.083	
A0	6.85	6.90	7.00	0.270	0.271	0.276	
В0	10.45	10.50	10.60	0.411	0.413	0.417	
K0	2.68	2.78	2.88	0.105	0.109	0.113	
Т	0.24		0.27	0.009		0.011	
t1	0.10			0.004			
10P0	39.80	40.00	40.20	1.567	1.575	1.583	